# 1Mx36 & 2Mx18-Bit Synchronous Pipelined Burst SRAM

#### **FEATURES**

- Synchronous Operation.
- 2 Stage Pipelined operation with 4 Burst.
- On-Chip Address Counter.
- Self-Timed Write Cycle.
- · On-Chip Address and Control Registers.
- VDD= 3.3V +0.165V/-0.165V Power Supply.
- I/O Supply Voltage 3.3V +0.165V/-0.165V for 3.3V I/O or 2.5V+0.4V/-0.125V for 2.5V I/O.
- 5V Tolerant Inputs Except I/O Pins.
- Byte Writable Function.
- Global Write Enable Controls a full bus-width write.
- Power Down State via ZZ Signal.
- LBO Pin allows a choice of either a interleaved burst or a linear burst.
- Three Chip Enables for simple depth expansion with No Data Contention only for TQFP; 2cycle Enable, 1cycle Disable.
- Asynchronous Output Enable Control.
- ADSP, ADSC, ADV Burst Control Pins.
- TTL-Level Three-State Output.
- 100-TQFP-1420A / 119BGA(7x17 Ball Grid Array Package)

### **FAST ACCESS TIMES**

PARAMETER	Symbol	-25	-22	-20	Unit
Cycle Time	tCYC	4.0	4.4	5.0	ns
Clock Access Time	tCD	2.6	2.8	3.1	ns
Output Enable Access Time	tOE	2.6	2.8	3.1	ns

### **GENERAL DESCRIPTION**

The K7A323609M and K7A321809M are 37,748,736-bit Synchronous Static Random Access Memory designed for high performance second level cache of Pentium and Power PC based System.

It is organized as 1M(2M) words of 36(18) bits and integrates address and control registers, a 2-bit burst address counter and added some new functions for high performance cache RAM applications;  $\overline{\text{GW}}$ ,  $\overline{\text{BW}}$ ,  $\overline{\text{LBO}}$ , ZZ. Write cycles are internally self-timed and synchronous.

Full bus-width write is done by  $\overline{GW}$ , and each byte write is performed by the combination of  $\overline{WE}x$  and  $\overline{BW}$  when  $\overline{GW}$  is high. And with  $\overline{CS}_1$  high,  $\overline{ADSP}$  is blocked to control signals

Burst cycle can be initiated with either the address status processor( $\overline{ADSP}$ ) or address status cache controller( $\overline{ADSC}$ ) inputs. Subsequent burst addresses are generated internally in the system's burst sequence and are controlled by the burst address advance( $\overline{ADV}$ ) input.

LBO pin is DC operated and determines burst sequence(linear or interleaved).

ZZ pin controls Power Down State and reduces Stand-by current regardless of CLK.

The K7A323609M and K7A321809M are fabricated using SAMSUNG's high performance CMOS technology and is available in a 100pin TQFP and 119BGA package. Multiple power and ground pins are utilized to minimize ground bounce

## LOGIC BLOCK DIAGRAM



